

MMBFU310LT1G

JFET Transistor

N-Channel

Features

- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	25	Vdc
Gate-Source Voltage	V_{GS}	25	Vdc
Gate Current	I_G	10	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

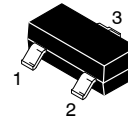
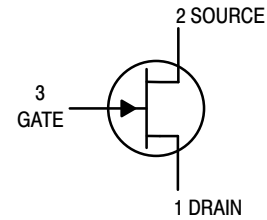
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225	mW
		1.8	mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.



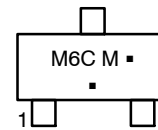
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SOT-23 (TO-236AB)
CASE 318-08
STYLE 10

MARKING DIAGRAM



M6C = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMBFU310LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBFU310LT1G

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Gate-Source Breakdown Voltage - ($I_G = -1.0 \mu\text{A}$, $V_{DS} = 0$)	$V_{(BR)GSS}$	-25	-	Vdc
Gate 1 Leakage Current - ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$)	I_{G1SS}	-	-150	pA
Gate 2 Leakage Current - ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$, $T_A = 125^\circ\text{C}$)	I_{G2SS}	-	-150	nA
Gate Source Cutoff Voltage - ($V_{DS} = 10 \text{ Vdc}$, $I_D = 1.0 \text{ nA}$)	$V_{GS(off)}$	-2.5	-6.0	Vdc

ON CHARACTERISTICS

Zero-Gate-Voltage Drain Current - ($V_{DS} = 10 \text{ Vdc}$, $V_{GS} = 0$)	I_{DSS}	24	60	mA
Gate-Source Forward Voltage - ($I_G = 10 \text{ mA}$, $V_{DS} = 0$)	$V_{GS(f)}$	-	1.0	Vdc

SMALL-SIGNAL CHARACTERISTICS

Forward Transfer Admittance - ($V_{DS} = 10 \text{ Vdc}$, $I_D = 10 \text{ mA}$, $f = 1.0 \text{ kHz}$)	$ Y_{fs} $	10	18	mmhos
Output Admittance - ($V_{DS} = 10 \text{ Vdc}$, $I_D = 10 \text{ mA}$, $f = 1.0 \text{ kHz}$)	$ y_{os} $	-	250	μmhos
Input Capacitance - ($V_{GS} = -10 \text{ Vdc}$, $V_{DS} = 0 \text{ Vdc}$, $f = 1.0 \text{ MHz}$)	C_{iss}	-	5.0	pF
Reverse Transfer Capacitance - ($V_{GS} = -10 \text{ Vdc}$, $V_{DS} = 0 \text{ Vdc}$, $f = 1.0 \text{ MHz}$)	C_{rss}	-	2.5	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

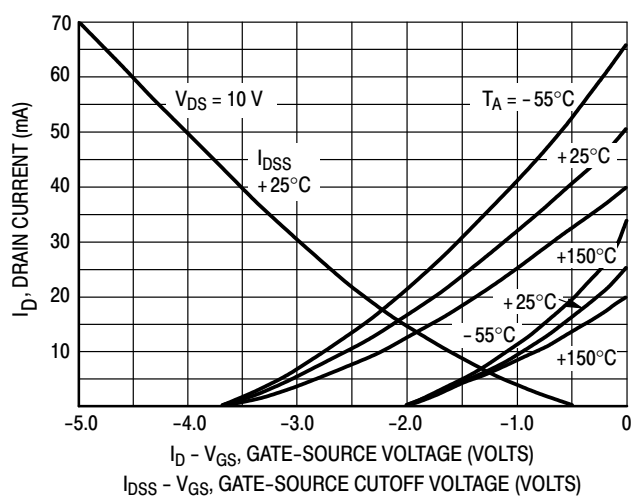


Figure 1. Drain Current and Transfer Characteristics vs Gate-Source Voltage

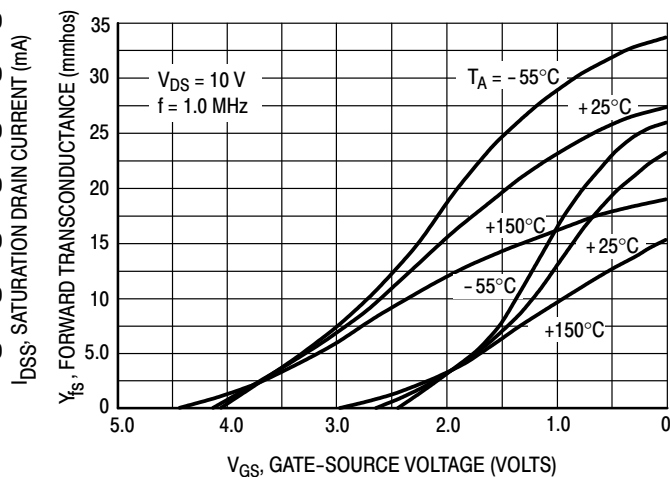


Figure 2. Forward Transconductance vs Gate-Source Voltage

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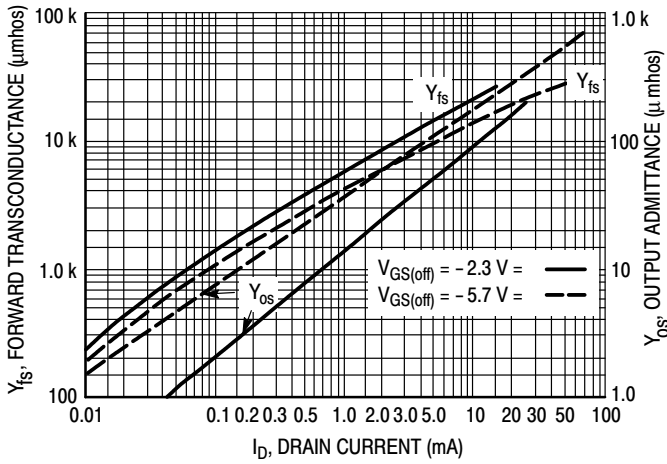


Figure 3. Common-Source Output Admittance and Forward Transconductance vs Drain Current

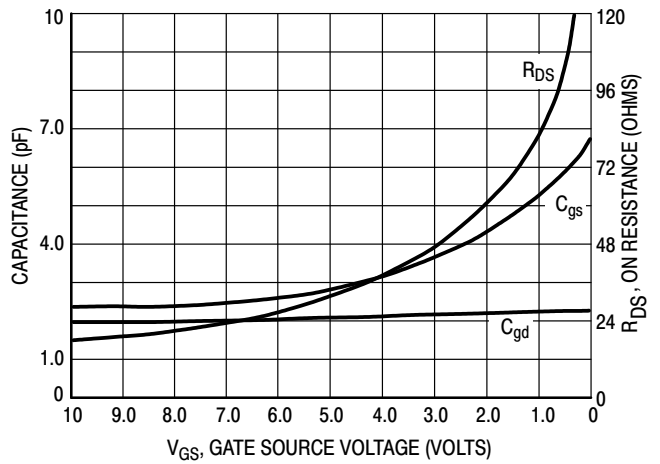


Figure 4. On Resistance and Junction Capacitance vs Gate-Source Voltage

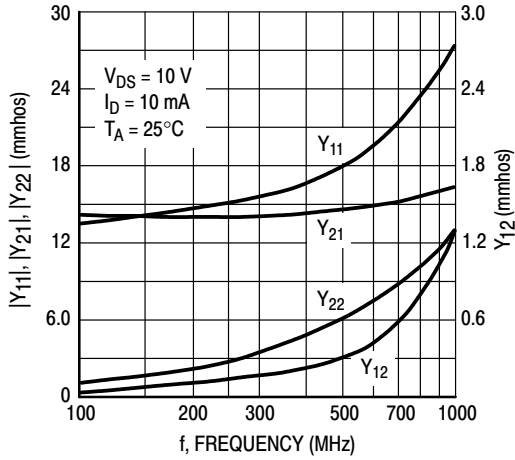


Figure 5. Common-Gate Y Parameter Magnitude vs Frequency

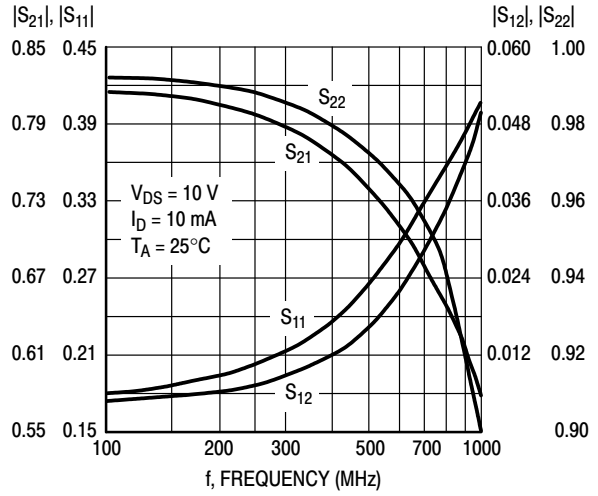


Figure 6. Common-Gate S Parameter Magnitude vs Frequency

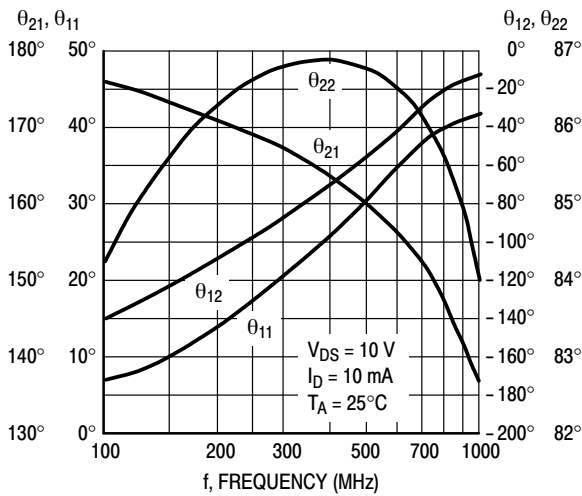


Figure 7. Common-Gate Y Parameter Phase-Angle vs Frequency

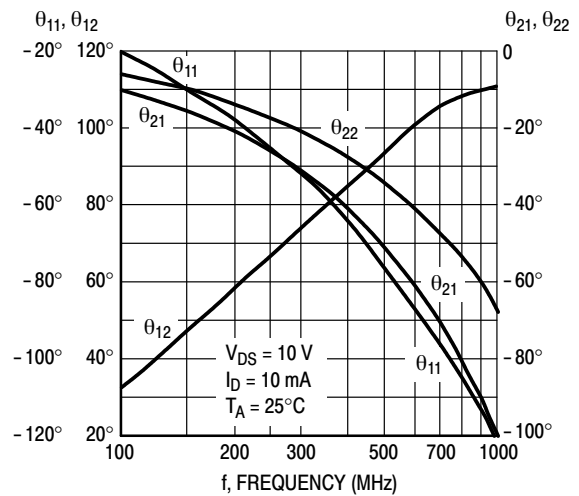


Figure 8. S Parameter Phase-Angle vs Frequency

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®



SOT-23 (TO-236)
CASE 318-08
ISSUE AS

DATE 30 JAN 2018

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
c	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
T	0°	---	10°	0°	---	10°

RECOMMENDED SOLDERING FOOTPRINT



GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

- | | | | |
|---|---|---|--|
| STYLE 1 THRU 5:
CANCELLED | STYLE 6:
PIN 1. BASE
2. EMITTER
3. COLLECTOR | STYLE 7:
PIN 1. EMITTER
2. BASE
3. COLLECTOR | STYLE 8:
PIN 1. ANODE
2. NO CONNECTION
3. CATHODE |
| STYLE 9:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 10:
PIN 1. DRAIN
2. SOURCE
3. GATE | STYLE 11:
PIN 1. ANODE
2. CATHODE
3. CATHODE-ANODE | STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE |
| STYLE 13:
PIN 1. SOURCE
2. DRAIN
3. GATE | STYLE 14:
PIN 1. CATHODE
2. GATE
3. ANODE | STYLE 15:
PIN 1. GATE
2. CATHODE
3. ANODE | STYLE 16:
PIN 1. ANODE
2. CATHODE
3. CATHODE |
| STYLE 17:
PIN 1. NO CONNECTION
2. ANODE
3. CATHODE | STYLE 18:
PIN 1. NO CONNECTION
2. CATHODE
3. ANODE | STYLE 19:
PIN 1. CATHODE
2. ANODE
3. CATHODE-ANODE | STYLE 20:
PIN 1. CATHODE
2. ANODE
3. GATE |
| STYLE 21:
PIN 1. GATE
2. SOURCE
3. DRAIN | STYLE 22:
PIN 1. RETURN
2. OUTPUT
3. INPUT | STYLE 23:
PIN 1. ANODE
2. ANODE
3. CATHODE | STYLE 24:
PIN 1. GATE
2. DRAIN
3. SOURCE |
| STYLE 25:
PIN 1. ANODE
2. CATHODE
3. GATE | STYLE 26:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION | STYLE 27:
PIN 1. CATHODE
2. CATHODE
3. CATHODE | STYLE 28:
PIN 1. ANODE
2. ANODE
3. ANODE |

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